

Electronic Patent Application Fee Transmittal				
Application Number:		10552370		
Filing Date:		26-Jul-2006		
Title of Invention:		SOAP-MOLDING DIE		
First Named Inventor/Applicant Name:		Takashi Nakano		
Filer:		Marvin Jay Spivak/Mimi Chanthaphone		
Attorney Docket Number:		279330US3PCT		
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
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Utility Appl issue fee	1501	1	1510	1510
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Printed copy of patent - no color	8001	3	3	9
Total in USD (\$)				1819